



## Features

- For surface mounted applications in order to optimize board space
- Low profile package
- Built-in strain relief
- Glass passivated junction
- Low inductance
- Excellent clamping capability
- 600W peak pulse power capability at 10/1000 $\mu$ s waveform, repetition rate (duty cycle): 0.01%
- Fast response time
- Typical IR less than 1 $\mu$ A above 12V
- High Temperature soldering: 260 $^{\circ}$ C/10 seconds at terminals
- Plastic package has underwriters laboratory flammability 94V-0



SMB  
(DO-214AA)

## Mechanical Data

- Case : JEDEC DO-214AA/SMB molded plastic body
- Terminals : Solderable per MIL-STD-750, Method 2026
- Polarity : Polarity symbol marking on body
- Mounting Position: Any
- Weight: 0.003 ounce, 0.095 grams

## Applications

- I/O interface
- AC/D Cpower supply
- Low frequency signal transmission line (RS232, RS485, etc.)

## Maximum Ratings (Ta=25 $^{\circ}$ C unless otherwise noted)

|                                                                                                                   |                                    |             |                |
|-------------------------------------------------------------------------------------------------------------------|------------------------------------|-------------|----------------|
| Peak pulse power dissipation at 10/1000 $\mu$ s waveform (Note1, Note2, Fig.1)                                    | P <sub>PPM</sub>                   | 600         | W              |
| Peak pulse current of at 10/1000 $\mu$ s waveform (Note 1, Fig.3)                                                 | I <sub>PPM</sub>                   | 0.9         | A              |
| Steady state power dissipation at T <sub>A</sub> =50 $^{\circ}$ C (Fig.5)                                         | P <sub>M(AV)</sub>                 | 5.0         | W              |
| Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load, (JEDEC Method) (Note3, Fig.6) | I <sub>FSM</sub>                   | 100         | A              |
| Operating junction and Storage Temperature Range.                                                                 | T <sub>J</sub> , T <sub>STG</sub>  | -65 to +150 | $^{\circ}$ C   |
| Typical thermal resistance junction to lead                                                                       | R <sub><math>\theta</math>JL</sub> | 20          | $^{\circ}$ C/W |
| Typical thermal resistance junction to ambient                                                                    | R <sub><math>\theta</math>JA</sub> | 100         | $^{\circ}$ C/W |

Notes:1. Non-repetitive current pulse, per Fig.3 and derated above TA=25 $^{\circ}$ C per Fig.2.  
2. Mounted on 5.0mm $\times$ 5.0mm (0.03mm thick) copper pads to each terminal.  
3. 8.3ms single half sine-wave, or equivalent square wave, duty cycle=4 pulses per minutes maximum.

## Electrical Characteristics (Ta=25 $^{\circ}$ C)

| Part Number    |                 | Device Marking Code |      | Reverse Stand- Off Voltage | Breakdown Voltage @I <sub>T</sub> | Test Current        | Maximum Clamping Voltage @I <sub>PP</sub> | Peak Pulse Current  | Reverse Leakage @V <sub>RWM</sub> |
|----------------|-----------------|---------------------|------|----------------------------|-----------------------------------|---------------------|-------------------------------------------|---------------------|-----------------------------------|
| Unidirectional | Bidirectional   | UNI                 | BI   | V <sub>RWM</sub> (V)       | V <sub>BR</sub> (V)               | I <sub>T</sub> (mA) | V <sub>C</sub> (V)                        | I <sub>PP</sub> (A) | I <sub>R</sub> ( $\mu$ A)         |
| P6SMB480A/TR13 | P6SMB480CA/TR13 | 480A                | 480C | 408.00                     | 456.0-504.0                       | 1                   | 658.0                                     | 0.9                 | 1                                 |



## Ratings and Characteristic Curves ( $T_A=25^{\circ}\text{C}$ unless otherwise noted)

Figure 1. Peak Pulse Power Rating Curve

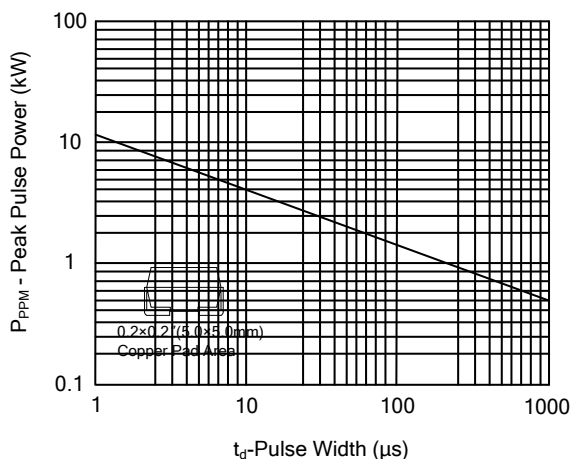


Figure 2. Pulse Derating Curve

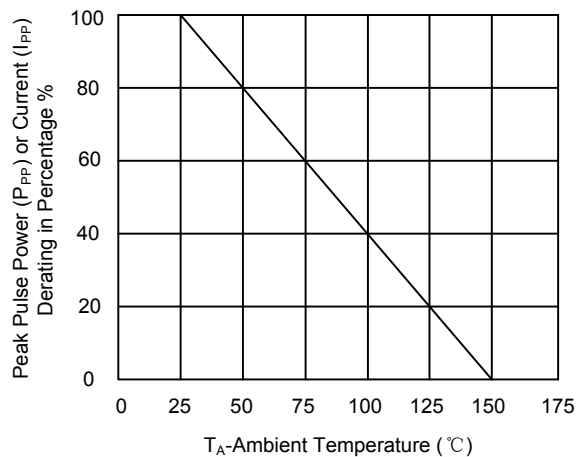


Figure 3. Pulse Waveform

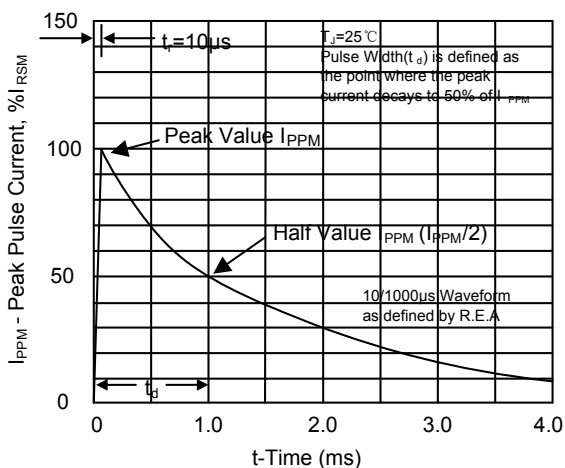


Figure 4. Typical Junction Capacitance

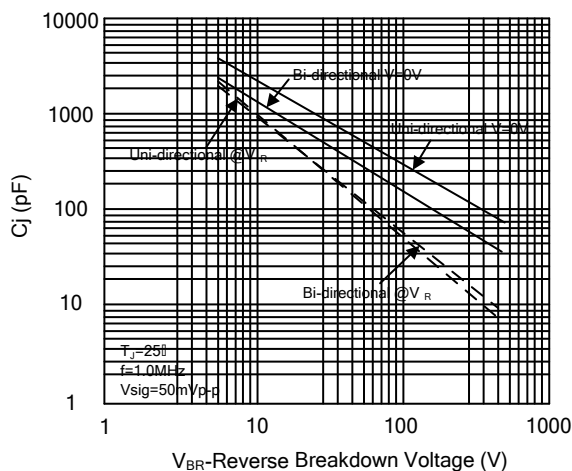


Figure 5. Steady State Power Dissipation Derating Curve

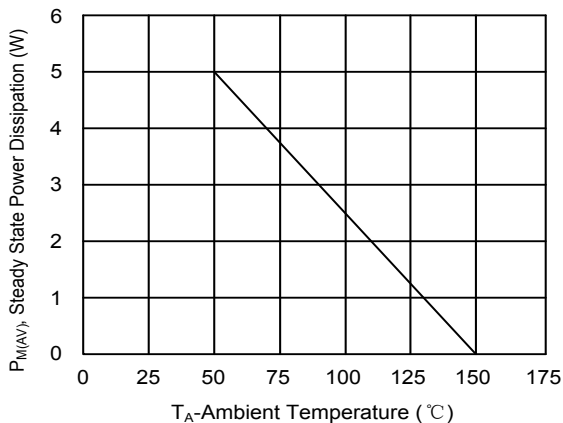
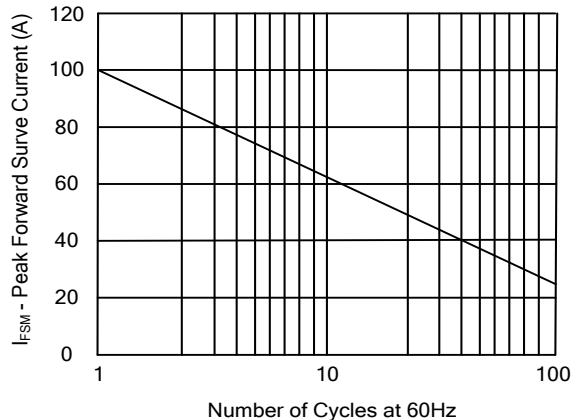
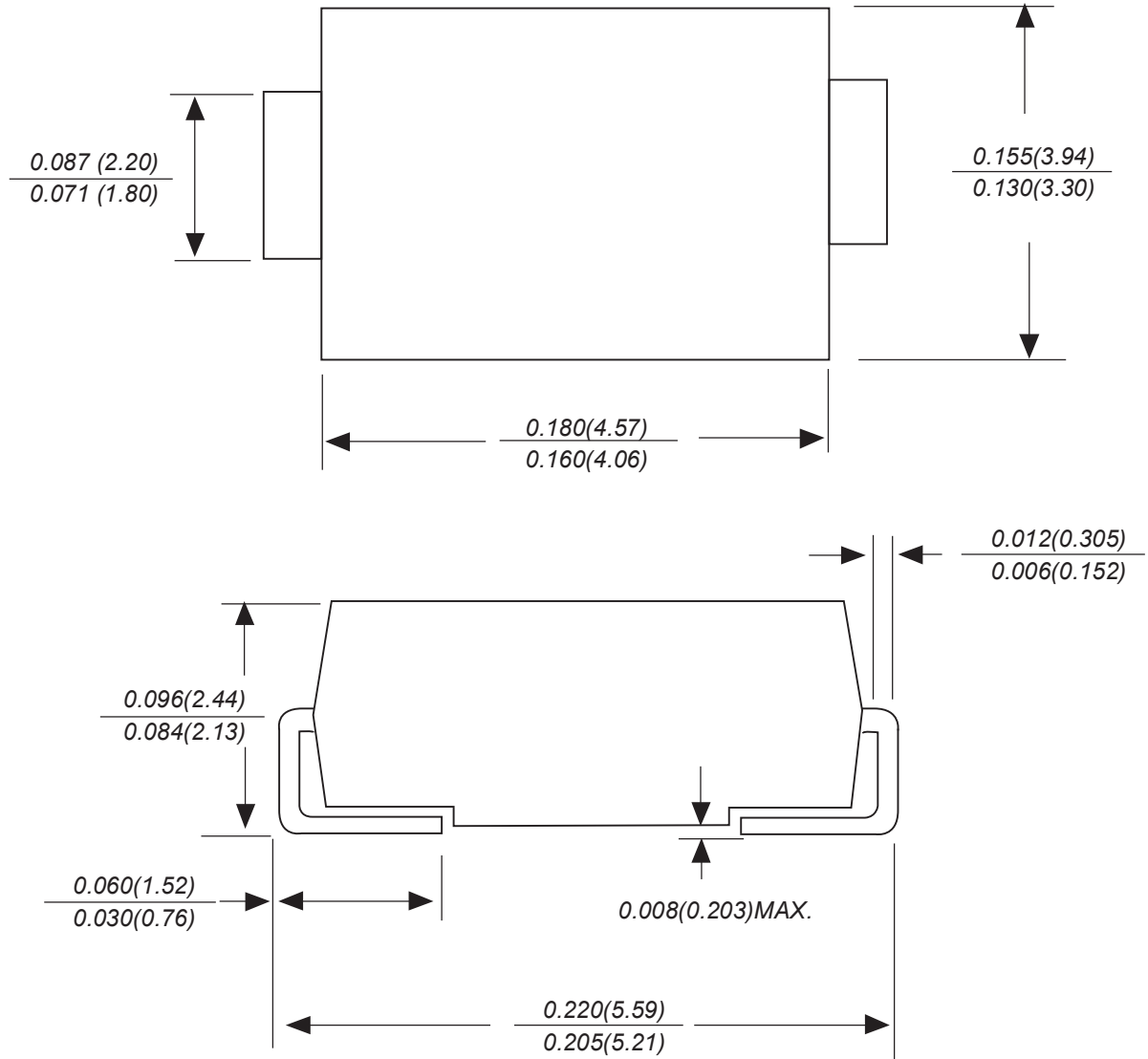


Figure 6. Maximum Non-Repetitive Forward Surge Current Uni-Directional Only





**Package Outline Dimensions**  
**SMB(DO-214AA)**



*Dimensions in inches and (millimeters)*



### **Attention**

- Any and all HUA XUAN YANG ELECTRONICS products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your HUA XUAN YANG ELECTRONICS representative nearest you before using any HUA XUAN YANG ELECTRONICS products described or contained herein in such applications.
- HUA XUAN YANG ELECTRONICS assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein.
- Specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- HUA XUAN YANG ELECTRONICS CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all HUA XUAN YANG ELECTRONICS products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of HUA XUAN YANG ELECTRONICS CO.,LTD.
- Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production. HUA XUAN YANG ELECTRONICS believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the HUA XUAN YANG ELECTRONICS product that you intend to use.